PCN# : P562AAB
Issue Date: June 26, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below. This is defined as a Discrete device.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications.

This Fabrication site change will be completed by June 30, 2015.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Description of Change (From):
- Fabrication Site: Fairchild Salt Lake City, UT 6-inch wafer manufacturing

Description of Change (To):
- Fabrication Site: Fairchild, Bucheon, Korea 8-inch wafer manufacturing

Reason for Change:

Fabrication Site: Improvement in cost competency to allow Fairchild to sustain long term commercial support to Apple for our discrete, low-voltage FET products.

Affected Product(s): Please refer to the list of affected products on the next page. This list is based on an analysis of your company’s procurement history.

FABRICATION:

FROM Site	To Sites	Locations
Fairchild, Salt Lake City, UT 6 inch	Fairchild, Bucheon 8-inch	Bucheon, Korea

PCN Product List Addendum for:

Customer: Apple

Category	Apple Part #	FCS Part #	Fab	Assembly	Reliability Reports
Running	376S1147	FDPC1012S	Fairchild, Bucheon	(no change)	(see attached reports)